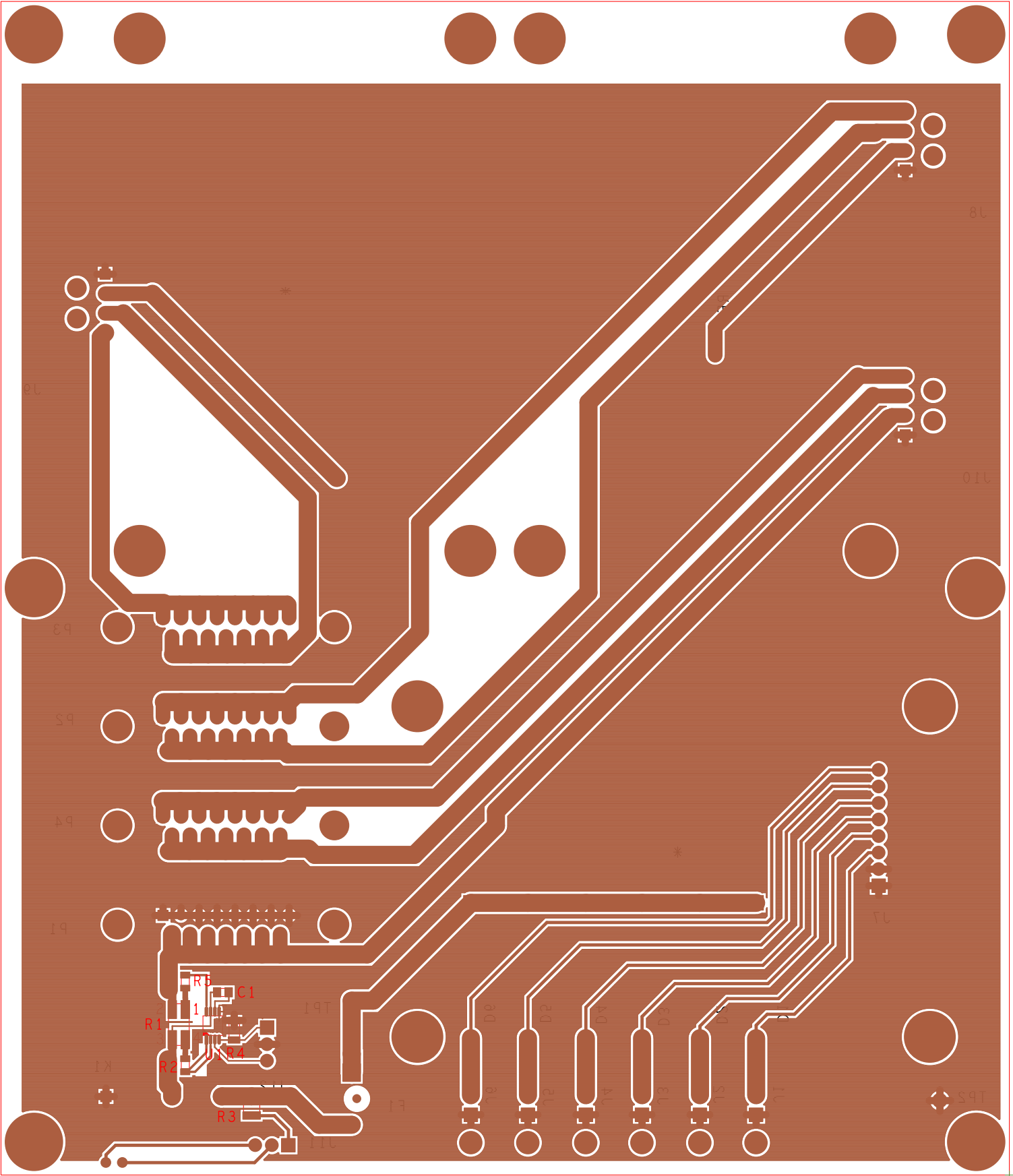




1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6013A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:  
a. OVERALL THICKNESS TO BE 0.062" +/- 0.003"  
b. PLANE LAYERS TO BE 1 OZ. COPPER.  
c. SIGNAL LAYERS TO BE 1/2 OZ. COPPER.  
d. FR4 PER IPC 4101B\24 \26 OR \28
4. LEGEND:  
a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:  
a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-2M-840 CLASS H, COLOR BLACK, BOTH SIDES.
6. PLATING FINISH:  
a. HOT AIR SOLDER LEVELING (HASL) 2N63A 2uPb SOLDER.
7. PROCESS ALLOWANCES:  
a. MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%  
b. HOLE DIMENSIONS APPLY AFTER PLATING.  
c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.  
d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".  
e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.003".  
f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0\015" MAX.  
g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.
- CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

| DRILL CHART: TOP + |      |  |
|--------------------|------|--|
| ALL UNITS ARE IN   |      |  |
| FIGURE             | SIZE |  |
| T20                | 50.0 |  |
| □                  | 35.0 |  |
| T43                | 43.0 |  |
| T44                | 44.0 |  |
| T60                | 60.0 |  |